

	Type	L #	Hits	Search Text	DBs	Time Stamp
1	IS&R	L1	4560	(438/107,109,612,614).CCLS.	US-PGPUB; USPAT; EPO; DERWE NT	2007/07/26 15:07
2	BRS	L2	473	1 and (first second primary secondary) adj substrate	US-PGPUB; USPAT; EPO; DERWE NT	2007/07/26 15:08
3	BRS	L3	240	2 and ("grid array" "ball grid" "solder ball")	US-PGPUB; USPAT; EPO; DERWE NT	2007/07/26 15:09
4	BRS	L4	165	3 and @ad<"20040312"	US-PGPUB; USPAT; EPO; DERWE NT	2007/07/26 15:10
5	BRS	L5	25	4 and (peripheral secondary pin) near5 contact	US-PGPUB; USPAT; EPO; DERWE NT	2007/07/26 15:12
6	BRS	L6	61321	(first second primary secondary) adj substrate	US-PGPUB; USPAT; EPO; DERWE NT	2007/07/26 15:15

	Type	L #	Hits	Search Text	DBs	Time Stamp
7	BRS	L7	5336	6 and (pcb "printed circuit board")	US-PGPUB; USPAT; EPO; DERWE NT	2007/07/26 15:16
8	BRS	L8	1582	7 and ("grid array" "ball grid" "solder ball")	US-PGPUB; USPAT; EPO; DERWE NT	2007/07/26 15:16
9	BRS	L9	251	8 and (peripheral secondary pin) near5 contact	US-PGPUB; USPAT; EPO; DERWE NT	2007/07/26 15:16
10	BRS	L10	174	9 and @ad<"20040312"	US-PGPUB; USPAT; EPO; DERWE NT	2007/07/26 15:17
11	BRS	L11	64	10 and ground	US-PGPUB; USPAT; EPO; DERWE NT	2007/07/26 15:17
12	BRS	L12	54	11 and power	US-PGPUB; USPAT; EPO; DERWE NT	2007/07/26 15:17

	Type	L #	Hits	Search Text	DBs	Time Stamp
13	BRS	L13	19	12 and (first second primary secondary) adj contact	US- PGPUB; USPAT; EPO; DERWE NT	2007/07/26 15:20